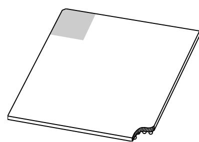


SOT604-1

plastic thermal enhanced ball grid array package; 504 balls; body 35 x 35 x 0.9 mm; heatsink

8 February 2016 — Package information

1. Package summary

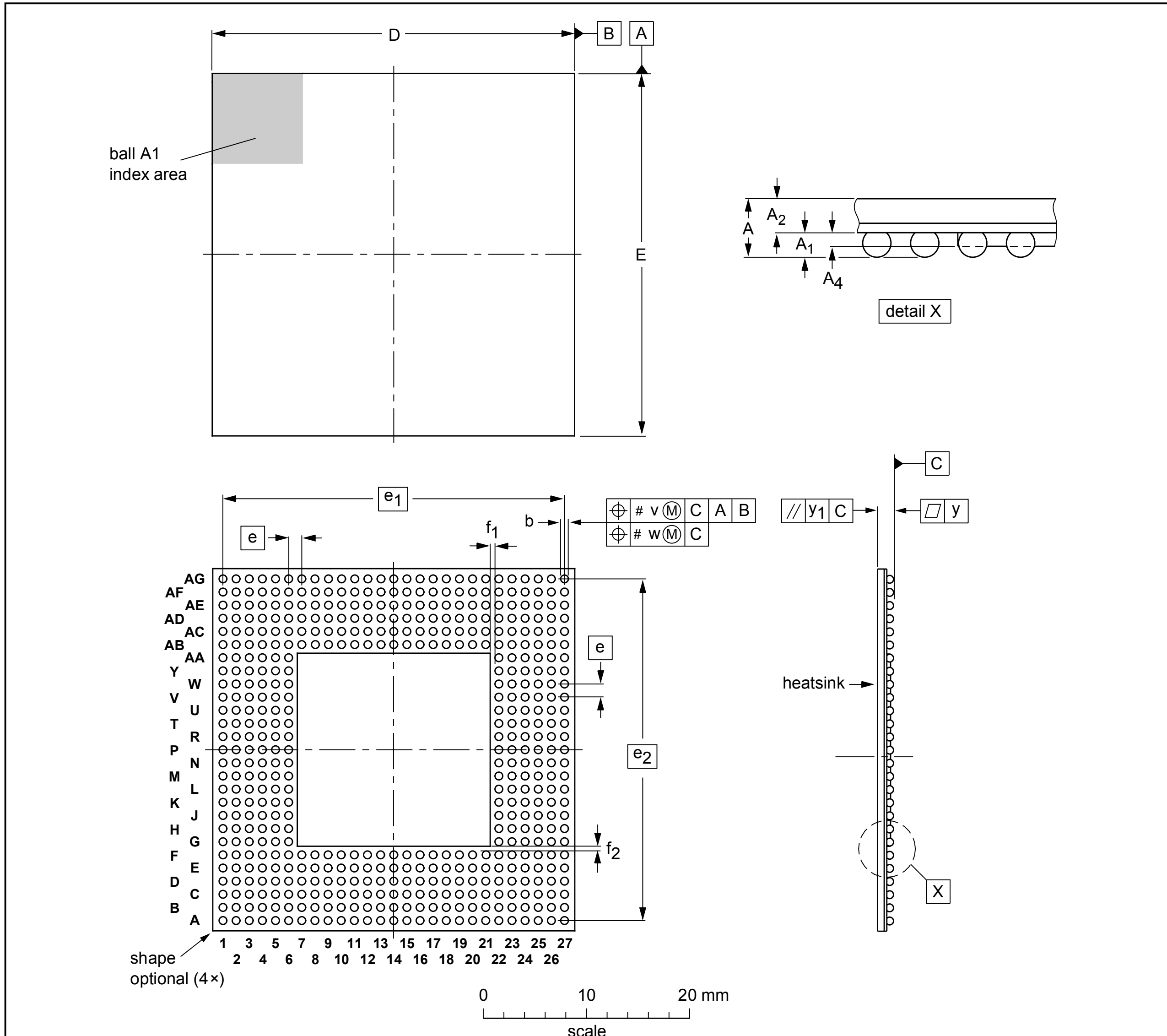
Terminal position code	B (bottom)
Package type descriptive code	HBGA504
Package type industry code	HBGA504
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	144E
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	17-3-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		34.8	-	35	35.2	mm
E	package width		34.8	-	35	35.2	mm
A	seated height		[tbd]	-	1.65	1.65	mm
A_2	package height		0.8	-	0.9	1	mm
n_2	actual quantity of termination		-	-	504	-	

2. Package outline

HLBGA504: plastic thermal enhanced low profile ball grid array package; 504 balls; body 35 x 35 x 0.9 mm; heatsink **SOT604-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_4 max.	b	D	E	e	e_1	e_2	v	w	y	y_1	f_1 min.	f_2 min.
mm	1.65	0.7 0.6	1.0 0.8	0.42	0.85 0.65	35.2 34.8	35.2 34.8	1.27	33.02	33.02	0.3	0.1	0.15	0.15	0.5	0.5

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT604-1	144E	MO-192	- - -			~~03-03-17~~ 10-08-10

Fig. 1. Package outline HBGA504 (SOT604-1)

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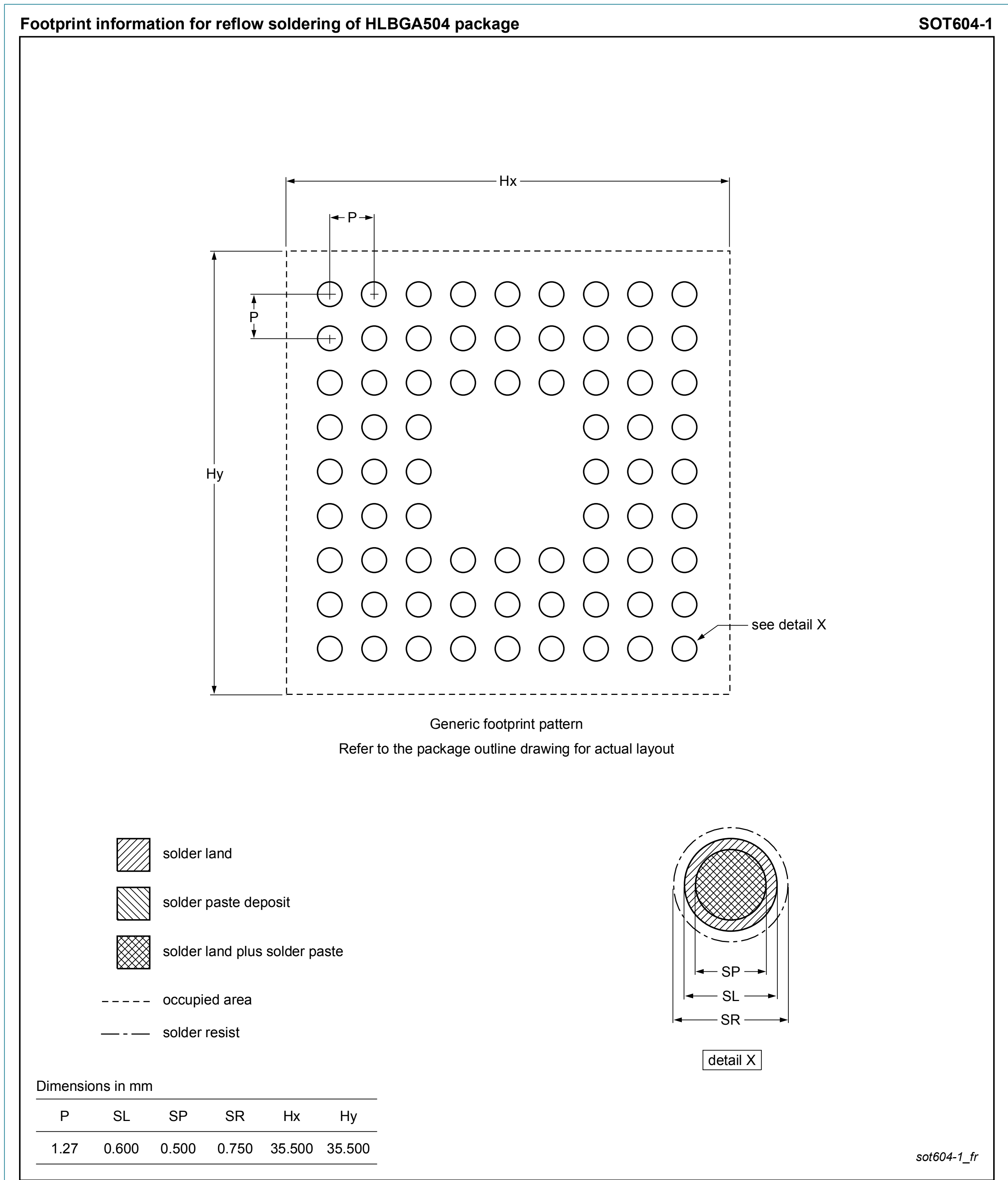
3. Soldering



P	SL	SP	SR	Hx	Hy
1.27	0.600	0.500	0.750	35.500	35.500

Fig. 2. Reflow soldering footprint for HBGA504 (SOT604-1)

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